



SOT1189-1

plastic, thermal enhanced extremely thin small outline package; 6 terminals; 0.5 mm pitch; 1.6 mm x 1.6 mm x 0.5 mm body

15 August 2018

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HXSON6
Package type industry code	DFN1616-6
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-08-2018
Manufacturer package code	SOT1189

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.5	1.6	1.7	mm
package width	1.5	1.6	1.7	mm
seated height	0.46	0.48	0.5	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	6	-	



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2 Package outline

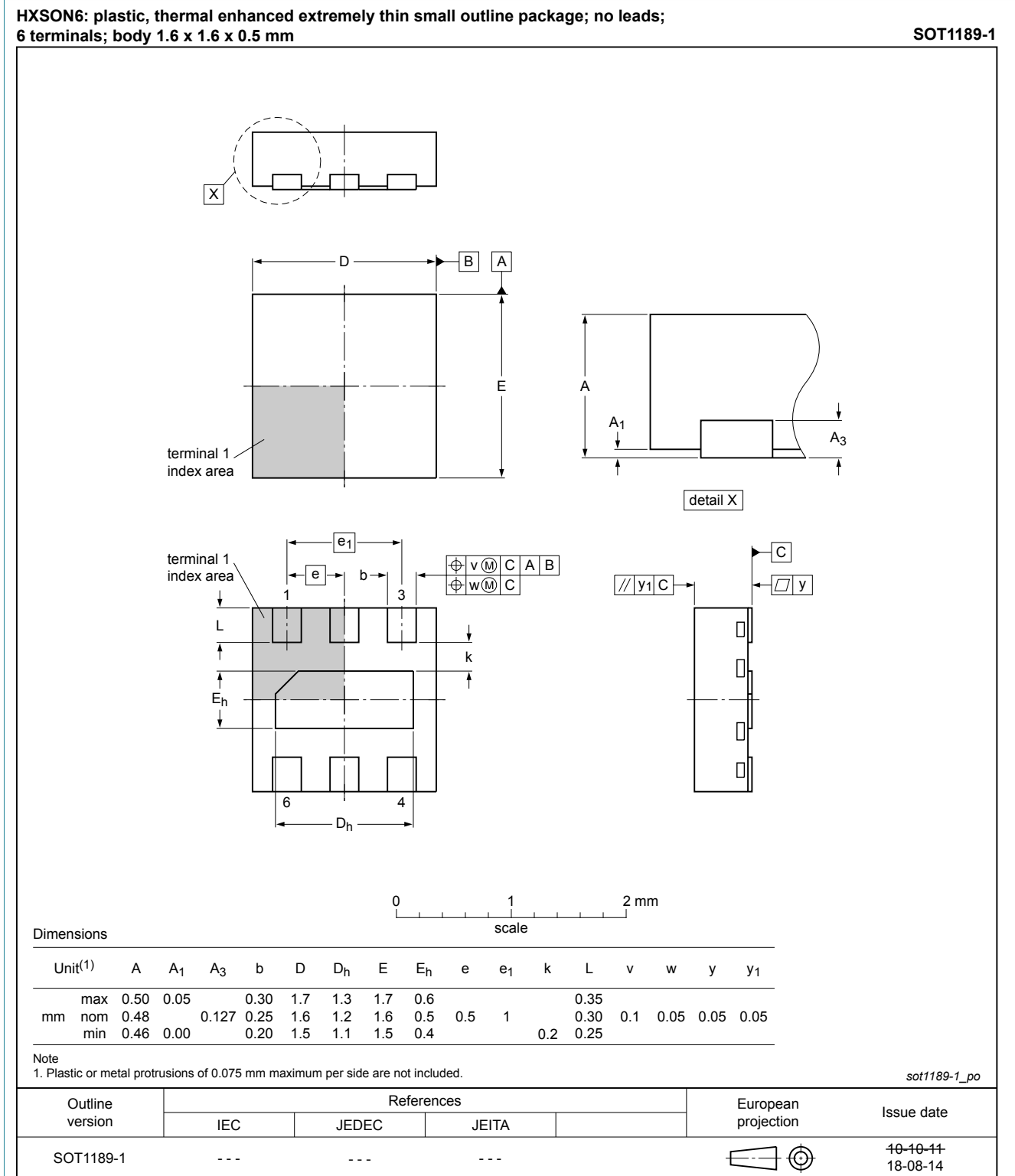


Figure 1. Package outline DFN1616-6 (SOT1189-1)

3 Soldering

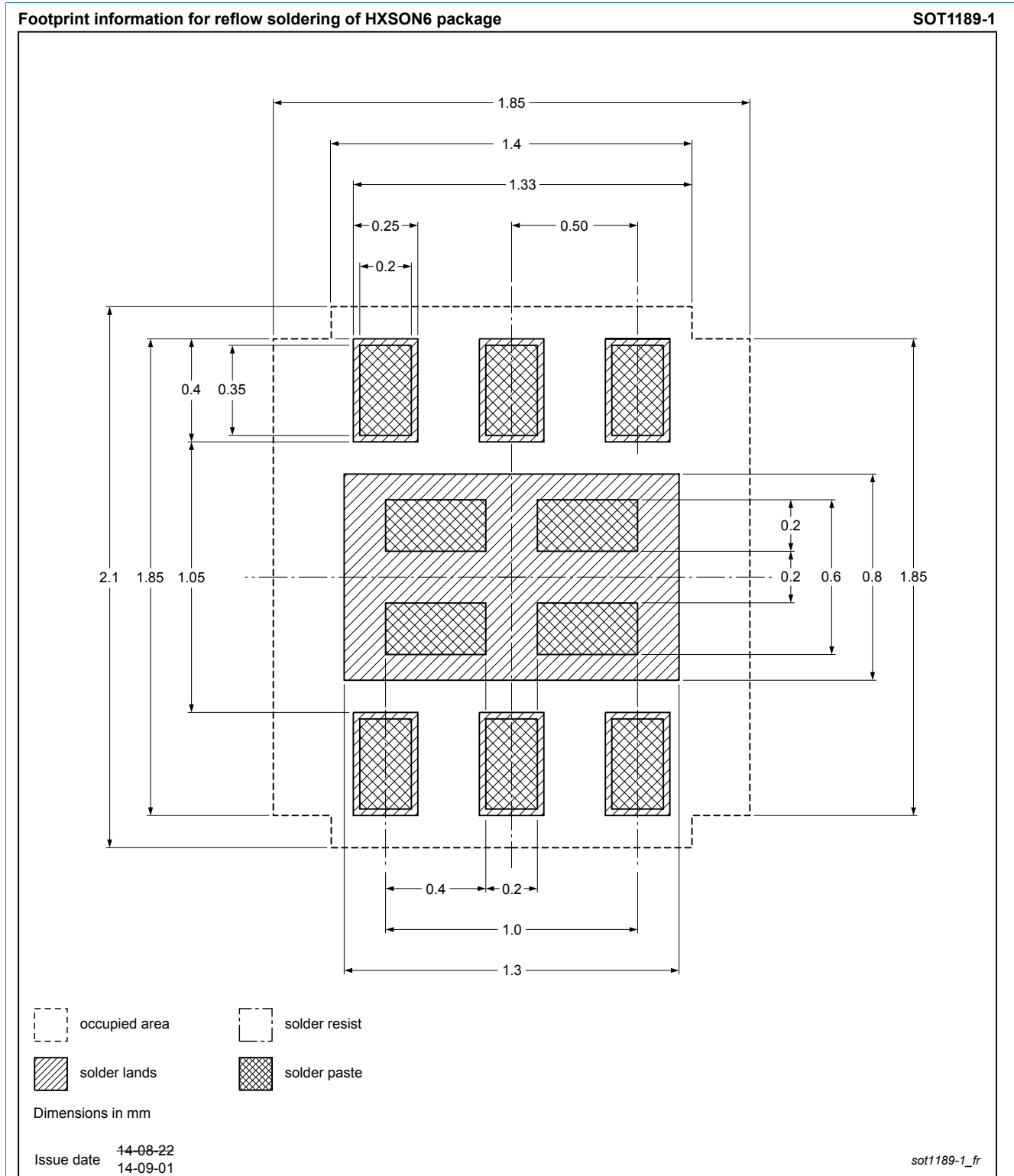


Figure 2. Reflow soldering footprint for DFN1616-6 (SOT1189-1)

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4 Legal information

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